TP200-H45-SF

AOK-TDS-254 Ver:A0

Silicone-free Gap Filler Pad

TP200-H45-SF is a silicone-free thermal conductive pad, specially designed and developed for organosilicon sensitive applications as a high thermal conductivity, high strength and flame retardant interface thermal conductive material, which can meet a variety of applications such as high compression, multiple rework, tear resistance, high frequency vibration and impact.

Features and Benefits

- Thermal Conductivity : 2.0 W/m·K
- No silicone oil precipitation or siloxane volatilization
- Well mechanical properties
- Weak viscosity, can increase viscosity on one side
- High electrical insulation

Typical Applications

- Optical fiber module
- Medical equipment
- Hard drive
- Optical precision equipment
- High-end industrial control equipment
- Automotive Sensors/Control Modules

Typical Properties

Attribute	Value	Test Method
Color	Green	Visual
Thickness (mm)	1.0 to 4.0	ASTM D374
Density (g/cc)	2.5	ASTM D792
Hardness (Shore 00)	45 to 55	ASTM D2240
Weight Loss (%)	⩽1.0	Filter paper adsorption @25% compression/125°C/48h
Usage temperature (°C)	-40 to 120	/
Flammability	V-0	UL 94
Storage period (Months)	12	Temperature <40°C avoid extrusion and exposure to the sun
Electrical		
Breakdown Voltage (kV/mm)	⩾6.0	ASTM D149
Dielectric Constant	7.3	ASTM D150
Volume Resistivity (Ω·cm)	1.5×10^{10} to 10^{11}	ASTM D257
Thermal		
Thermal Conductivity (W/(m·K))	2.0	ISO 22007-2

AOK 傲川科技 AOCHUAN TECHNOLOGY